



TET ESTEL AS
ESTONIA

January
2017

Series
TF333-250

High Frequency Inverter grade
Capsule Thyristor
Type TF333-250

Low switching losses
Low reverse recovery charge
Distributed amplified gate for high di/dt

Maximum mean on-state current	I_{TAV} 250 A							
Maximum repetitive peak off-state and reverse voltage	U_{DRM} 1200 ÷ 2200 V							
Turn-off time	U_{RRM} 25; 32; 40 μs							
U_{DRM}, U_{RRM}, V	1200	1300	1400	1500	1600	1800	2000	2200
Voltage code	12	13	14	15	16	18	20	22
$T_{vj}, ^\circ C$	- 60 ÷ 125							

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	TF333-250	Conditions
I_{TAV}	Mean on-state current	A	250 445	$T_c=90^\circ C,$ $T_c=55^\circ C,$ 180° half-sine wave, 50 Hz
I_{TRMS}	RMS on-state current	A	392	$T_c=90^\circ C$
I_{TSM}	Surge on-state current	kA	6,3 7,0	$T_{vj}=125^\circ C$ $T_{vj}=25^\circ C$ tp=10 ms $U_R=0$
I^2t	Limiting load integral	kA^2s	198 245	$T_{vj}=125^\circ C$ $T_{vj}=25^\circ C$
U_{DRM}, U_{RRM}	Repetitive peak off-state and reverse voltage	V	1200÷2200	$T_j \min \leq T_{vj} \leq T_{jM}$ 180° half-sine wave, 50 Hz Gate open
U_{DSM}, U_{RSM}	Non-repetitive peak off-state and reverse voltage	V	1300÷2300	$T_j \min \leq T_{vj} \leq T_{jM}$ 180° half-sine wave tp=10 ms, Single pulse Gate open
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current : non - repetitive repetitive	A/ μ s	1000 500	$T_{vj}=125^\circ C ; U_D=0,67 U_{DRM},$ Gate pulse : 10V,5 $\Omega,$ 1 μ s rise time, 10 μ s
U_{RGM}	Peak reverse gate voltage	V	5	$T_j \min \leq T_{vj} \leq T_{jM}$
T_{stg}	Storage temperature	$^\circ C$	-60÷80	
T_{vj}	Junction temperature	$^\circ C$	-60÷125	

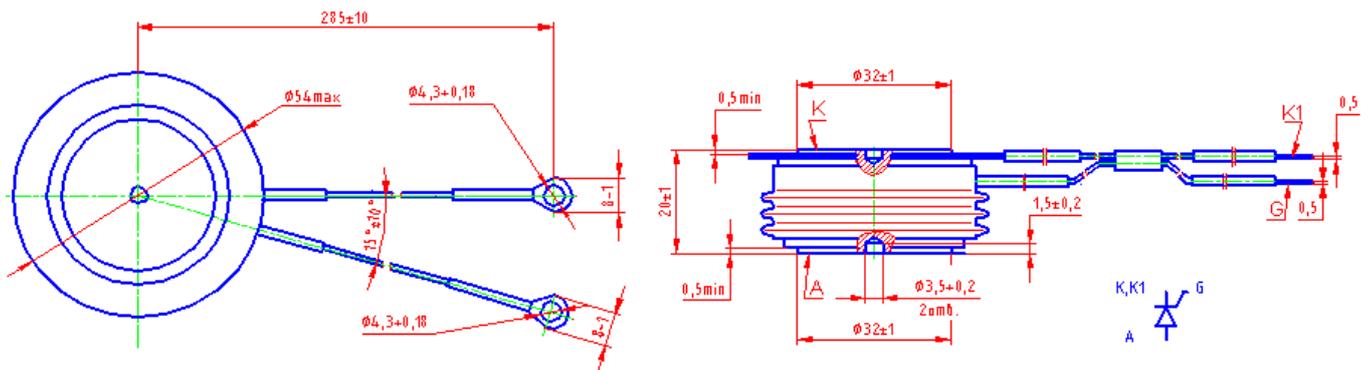
CHARACTERISTICS

U_{TM}	Peak on-state voltage	V	2,8	$T_{vj}=25^\circ C, I_{TM}=3,14 I_{TAV}$
$U_{T(TO)}$	Threshold voltage	V	1,6	$T_{vj}=125^\circ C$
R_T	On-state slope resistance	m Ω	1,7	1,57 $I_{TAV} < I_T < 4,71 I_{TAV}$
I_{DRM} I_{RRM}	Repetitive peak off-state and reverse current	mA	50 50	$T_{vj}=125^\circ C,$ $U_D = U_{DRM}$ $U_R = U_{RRM}$

CHARACTERISTICS				
Symbols and parameters		Units	TF333-250	Conditions
I_L	Latching current	A	5	$T_{vj}=25^{\circ}\text{C}, U_D=12\text{V}$ Gate pulse : 10V, 5 Ω , 1 μs rise time, 10 μs
I_H	Holding current	A	0,5	$T_{vj}=25^{\circ}\text{C}, U_D=12\text{V}$, Gate open
U_{GT}	Gate trigger direct voltage	V	2,5 5,0	$T_{vj}=25^{\circ}\text{C}$, $T_{vj}=-60^{\circ}\text{C}$
I_{GT}	Gate trigger direct current	A	0,3 0,85	$T_{vj}=25^{\circ}\text{C}$, $T_{vj}=-60^{\circ}\text{C}$
U_{GD}	Gate non-trigger direct voltage	V	0,25	$T_{vj}=125^{\circ}\text{C}$, $U_D = 0,67 U_{DRM}$
I_{GD}	Gate non-trigger direct current	mA	10	Direct gate current
t_{gd}	Delay time	μs	1,6	$T_{vj}=25^{\circ}\text{C}, U_D=500\text{V}$ $I_{TM} = 250 \text{ A}$
t_{gt}	Turn-on time	μs	2,5	Gate pulse : 10V, 5 Ω , 1 μs rise time, 10 μs
t_q	Turn-off time	μs	25 \div 40 32 \div 50	$T_{vj}=125^{\circ}\text{C}$, $I_{TM}=250 \text{ A}$ $di_R/dt = 10 \text{ A}/\mu\text{s}$, $U_R=100\text{V}$ $U_D = 0,67 U_{DRM}$ $du_D/dt=50 \text{ V}/\mu\text{s}$ $du_D/dt=200 \text{ V}/\mu\text{s}$
Q_{rr}	Recovered charge	μC	350	
t_{rr}	Reverse recovery time	μs	5,6	$T_{vj}=125^{\circ}\text{C}$, $I_{TM}=250 \text{ A}$
I_{rrm}	Peak reverse recovery current	A	125	$di_R/dt = 50 \text{ A}/\mu\text{s}$, $U_R=100\text{V}$
$(du_D/dt)_{crit}$	Critical rate of rise of off-state voltage	$\text{V}/\mu\text{s}$	500 1000	$T_{vj}=125^{\circ}\text{C}$, $U_D = 0,67 U_{DRM}$ Gate open
R_{thjc}	Thermal resistance junction to case	$^{\circ}\text{C}/\text{W}$	0,045	Direct current, double side cooled

ORDERING							
TF	333	250	20	7	5	3	
1	2	3	4	5	6	7	

1. Fast thyristor with interdigitated gate structure.
2. Design version.
3. Mean on-state current, A.
4. Voltage code (20=2000V).
5. Critical rate of rise of off-state voltage (6 $\geq 500 \text{ V}/\mu\text{s}$, 7 $\geq 1000 \text{ V}/\mu\text{s}$).
6. Group of turn-off time ($du_D/dt=50 \text{ V}/\mu\text{s}$, 3 $\leq 40 \mu\text{s}$, 4 $\leq 32 \mu\text{s}$, 5 $\leq 25 \mu\text{s}$).
7. Group of turn-on time (3 $\leq 2,5 \mu\text{s}$).



Mounting force : 9 \div 14 kN
Weight : 190 grams